Compliant with IEC 62474/ D9.00 Compliant to IEC 61249-2-21:2003

| MICROCHIP Semiconductor Device Type: JFA JFA 010 VDFN 3x3x0.9 NiPdAu | | | Termination Base Alloy: Copper Alloy (Cu) | | | Package Homogeneous Materials: 8.1 Electronics (e.g. pc boards, displays) | | | | J-STD-609A Product Marking and/or Pkg. Labeling e4 |
|---|--|--|--|--|---|--|---|---|--|--|
| Commoditation Devices Type. | 1 | "Contained In" | % Total | | | | | | | |
| Basic Substance | CAS Number | Sub-Component | Weight | mg/part | ppm | 15.50 | (mg) Total | Mold Compound | % ot Total Weight | 68.26 |
| Silica, fused | 60676-86-0 | Mold Compound | 61.434 | 13.946 | 614,340 | | Silica, fused | 60676-86-0 | 90.00 | |
| Epoxy Resin | Trade Secret | Mold Compound | 3.311 | 0.752 | 33,106 | | Epoxy Resin | Trade Secret | 4.85 | |
| Phenolic Resin | Trade Secret | Mold Compound | 3.311 | 0.752 | 33,106 | | Phenolic Resin | Trade Secret | 4.85 | |
| Carbon Black | 1333-86-4 | Mold Compound | 0.205 | 0.046 | 2,048 | | Carbon Black | 1333-86-4 | 0.30 | |
| Copper | 7440-50-8 | Lead Frame | 23.498 | 5.334 | 234,982 | | | Total | 100.00 | |
| Iron | 7439-89-6 | Lead Frame | 0.035 | 0.008 | 353 | 5.35 | (mg) Total | Lead Frame | % of Total Weight | 23.55 |
| Phosphorous | 7723-14-0 | Lead Frame | 0.009 | 0.002 | 94 | | Copper | 7440-50-8 | 99.78 | |
| Zinc (Metal) Silver | 7440-66-6 7440-22-4 | Lead Frame Die Attach | 0.007 0.785 | 0.002 0.178 | 71 7,854 | | Iron Phosphorous | 7439-89-6 7723-14-0 | 0.15 0.04 | |
| Epoxy resin | 68475-94-5 | Die Attach | 0.204 | 0.046 | 2.040 | | Zinc (Metal) | 7440-66-6 | 0.04 | |
| Copper(II) oxide | 1317-38-0 | Die Attach | 0.031 | 0.007 | 306 | Į. | Zirio (Wotai) | Total | 100.00 | |
| Silicon | 7440-21-3 | Duel Chip (Die) | 5.350 | 1.214 | 53.500 | 0.23 | (mg) Total | Die Attach | % of Total Weight | 1.02 |
| Gold | 7440-57-5 | Wire Bond | 0.610 | 0.138 | 6.100 | 0.20 | Silver | 7440-22-4 | 77.00 | 1.02 |
| Nickel | 7440-02-0 | Plating on external leads (pins) | 1.089 | 0.247 | 10.890 | | Epoxy resin | 68475-94-5 | 20.00 | |
| Palladium | 7440-05-3 | Plating on external leads (pins) | 0.061 | 0.014 | 605 | | Copper(II) oxide | 1317-38-0 | 3.00 | |
| Gold | 7440-57-5 | Plating on external leads (pins) | 0.061 | 0.014 | 605 | | | Total | 100.00 | |
| | | TOTALS: | 100.000 | 22,700 | 1.000.000 | 1.21 | Total (mg) | Duel Chip (Die) | % of Total Weight | 5.35 |
| | | IUIALS: | 100.000 | | 1,000,000 | | | | | |
| | aterials comply v | g Total Mass with EU Directives: 2002/95/EC (27 January 2003) End-of-Life Vehicles (ELV) without exemption (2 |) & Directive 2 | | ,, | | Doped Silicon | 7440-21-3 Total | 100.00 | 3.60 |
| 2015/863/EU (31 March 2015) and 2000/53/EC anpliance with the above EU Directives has been | naterials comply v and 2016/774/EU (n verified via inter | g Total Mass vith EU Directives: 2002/95/EC (27 January 2003) |) & Directive 2 ero) /or analytical te | 011/65/EU (08 | June 2011) | 0.14 | | 7440-21-3 | 100.00 | 0.61 |
| 2015/863/EU (31 March 2015) and 2000/53/EC an pliance with the above EU Directives has been chemical substance is absent from the list aborochip Technology Incorporated's knowledge a urity concentration of the chemical substance, | naterials comply vand 2016/774/EU (n verified via interve, the chemical sand belief as of the if any, is not belo | g Total Mass with EU Directives: 2002/95/EC (27 January 2003) End-of-Life Vehicles (ELV) without exemption (z rnal design controls, supplier declarations, and a substance is NOT an intentional ingredient in the e date of this document, there is no credible rea by the threshold of regulatory concern for any re- |) & Directive 2 tero) /or analytical te e semiconducte ison to believe egulatory schel | 011/65/EU (08 est data. or device and, that the unavo | June 2011) to the best of idable | | Doped Silicon | 7440-21-3 Total Wire Bond 7440-57-5 | 100.00 100.00 % of Total Weight 100.00 | |
| 2015/863/EU (31 March 2015) and 2000/53/EC an pliance with the above EU Directives has been chemical substance is absent from the list aborochip Technology Incorporated's knowledge a urity concentration of the chemical substance, | naterials comply wind 2016/774/EU (n verified via interve, the chemical stand belief as of the if any, is not belog JL94 V0 flammabi | g Total Mass with EU Directives: 2002/95/EC (27 January 2003) End-of-Life Vehicles (ELV) without exemption (2 rnal design controls, supplier declarations, and is substance is NOT an intentional ingredient in the e date of this document, there is no credible rea ow the threshold of regulatory concern for any re lity standard for plastics. You can access the UI |) & Directive 2 tero) /or analytical te e semiconducte ison to believe egulatory schel | 011/65/EU (08 est data. or device and, that the unavo | June 2011) to the best of idable | | Doped Silicon (mg) Total | 7440-21-3 Total Wire Bond | 100.00 100.00 % of Total Weight | |
| 2015/863/EU (31 March 2015) and 2000/53/EC an pliance with the above EU Directives has been chemical substance is absent from the list aborochip Technology Incorporated's knowledge aurity concentration of the chemical substance, ding compounds used by Microchip meet the Lort at http://ul.com/global/eng/pages/offerings/ii | naterials comply wand 2016/774/EU (n verified via interve, the chemical sand belief as of the firm of the complete of the com | g Total Mass with EU Directives: 2002/95/EC (27 January 2003) End-of-Life Vehicles (ELV) without exemption (2 rnal design controls, supplier declarations, and / substance is NOT an intentional ingredient in the e date of this document, there is no credible rea when the threshold of regulatory concern for any re lity standard for plastics. You can access the Ut als/plastics/ made from polyvinyl chloride (PVC) plastic. "Wi |) & Directive 2 ero) /or analytical te e semiconducto ison to believe egulatory schei L iQTM family o | 011/65/EU (08 est data. or device and, that the unavo me world-wide of databases to | June 2011) to the best of idable | 0.14 | Doped Silicon (mg) Total | 7440-21-3 Total Wire Bond 7440-57-5 | 100.00 100.00 % of Total Weight 100.00 | |
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